

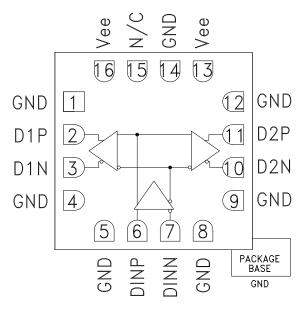


Typical Applications

The HMC724LC3 is ideal for:

- 16 G Fiber Channel
- RF ATE Applications
- Broadband Test & Measurement
- Serial Data Transmission up to 14 Gbps
- Clock Buffering up to 14 GHz

Functional Diagram



HMC724LC3

14 GBPS FAST RISE TIME 1:2 FANOUT BUFFER

Features

Inputs Terminated Internally to 50 Ohms Differential Inputs are DC Coupled Propagation Delay: 110 ps Fast Rise and Fall Times: 19 / 18 ps Power Dissipation: 300 mW 16 Lead Ceramic 3x3 mm SMT Package: 9 mm²

General Description

The HMC724LC3 is a 1:2 Fanout Buffer designed to support data transmission rates up to 14 Gbps, and clock frequencies as high as 14 GHz. All differential inputs and outputs are DC coupled and terminated on chip with 50 Ohm resistors to ground. The outputs may be used in either single ended or differential modes, and should be AC or DC coupled into 50 Ohm resistors connected to ground.

All differential inputs to the HMC724LC3 are CML and terminated on-chip with 50 Ohms to the positive supply, GND, and may be DC or AC coupled. The differential CMI outputs are source terminated to to 50 Ohms and may also be AC or DC coupled. Outputs can be connected directly to a 50 Ohm ground-terminated system or drive devices with CML logic input. The HMC724LC3 operates from a single -3.3 V supply and is available in ROHS-compliant 3x3 mm SMT package.

Parameter	Conditions	Min.	Тур.	Max	Units
Power Supply Voltage		-3.6	-3.3	-3.0	V
Power Supply Current			90		mA
Maximum Data Rate			14		Gbps
Maximum Clock Rate			14		GHz
Input Voltage Range		-1.5		0.5	V
Input Differential Range		0.1		2.0	Vp-p
Input Return Loss	Frequency <14 GHz		10		dB
Output Amplitude	Single-Ended, peak-to-peak		550		mVp-p
	Differential, peak-to-peak		1100		mVp-p
Output High Voltage			-10		mV
Output Low Voltage			-560		mV
Output Rise / Fall Time	Single-Ended, 20% - 80%		19 / 18		ps

Information furnished by Analog Devices is believed to be accurate and reliable. However, no responsibility is assumed by Analog Devices for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of Analog Devices. Trademarks and registered trademarks are the property of their respective owners.



HMC724LC3



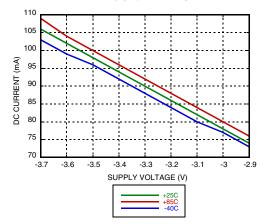
14 GBPS FAST RISE TIME **1:2 FANOUT BUFFER**

Electrical Specifications (continued)

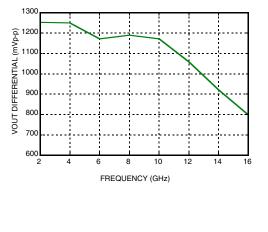
Parameter	Conditions	Min.	Тур.	Мах	Units
Output Return Loss	Frequency <14 GHz		10		dB
Small Signal Gain			27		dB
Random Jitter J _R	rms		0.2		ps rms
Deterministic Jitter, J _D	δ - δ, 2 ¹⁵ -1 PRBS input ^[1]		2	6	ps
Propagation Delay, td			110		ps
D1 to D2 Data Skew, t _{SKEW}			<2		ps

[1] Deterministic jitter measured at 13 GHz with a 300 mVp-p, 215-1 PRBS input sequence.

DC Current vs. Supply Voltage [1]



Output Differential Voltage vs. Frequency [3]



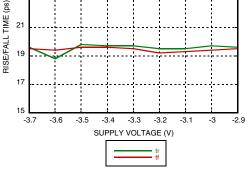
[1] Data rate = 13 Gbps

[2] Frequency = 10 GHz

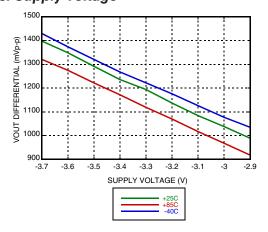
[3] Vee = 3.3 V

Information furnished by Analog Devices is believed to be accurate and reliable. However, no responsibility is assumed by Analog Devices for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of Analog Devices. Trademarks and registered trademarks are the property of their respective owners.

17



Output Differential Voltage vs. Supply Voltage [2]



Rise / Fall Time vs. Supply [1]

25

23

2



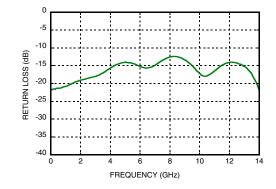
14 GBPS FAST RISE TIME

1:2 FANOUT BUFFER

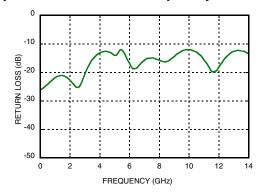
v03.0514



Output Return Loss vs. Frequency



Input Return Loss vs. Frequency



Information furnished by Analog Devices is believed to be accurate and reliable. However, no responsibility is assumed by Analog Devices for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of Analog Devices. Trademarks and registered trademarks are the property of their respective owners.

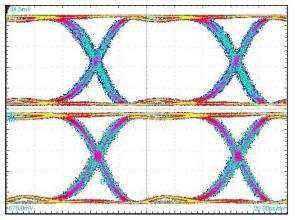


HMC724LC3

14 GBPS FAST RISE TIME 1:2 FANOUT BUFFER



Eye Diagram

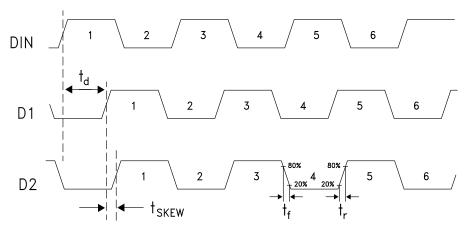


v03.0514

[1] Test Conditions:

Pattern generated with an Agilent N4903A Serial BERT. Eye Diagram presented on a Tektronix CSA 8000. Device input = 10 Gbps PN code, Vin = 300 mVp-p differential. Both output channels shown.

Timing Diagram



Information furnished by Analog Devices is believed to be accurate and reliable. However, no responsibility is assumed by Analog Devices for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of Analog Devices. Trademarks and registered trademarks are the property of their respective owners.





14 GBPS FAST RISE TIME 1:2 FANOUT BUFFER

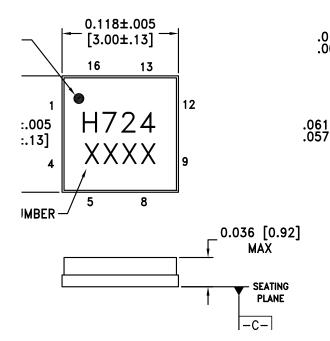
HMC724LC3

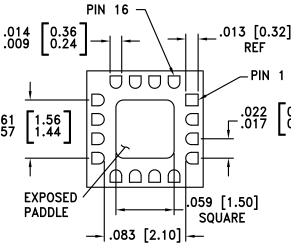
Absolute Maximum Ratings

	•
Power Supply Voltage (Vee)	-3.75 V to +0.5 V
Input Signals	-2 V to +0.5 V
Output Signals	-1.5 V to +1 V
Continuous Pdiss (T = 85 °C) (derate 17 mW/°C above 85 °C)	0.68 W
Thermal Resistance (R _{th j-p}) Worst case junction to package paddle	59 °C/W
Maximum Junction Temperature	125 °C
Storage Temperature	-65 °C to +150 °C
Operating Temperature	-40 °C to +85 °C
ESD Sensitivity (HBM)	Class 1C



Outline Drawing





NOTES:

- 1. PACKAGE BODY MATERIAL: ALUMINA
- 2. LEAD AND GROUND PADDLE PLATING:
- 30-80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKEL.
- 3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05 mm DATUM -C-
- 6. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.
- 7. PADDLE MUST BE SOLDERED TO GND.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[2]
HMC724LC3	Alumina, White	Gold over Nickel	MSL3 ^[1]	H724 XXXX

[1] Max peak reflow temperature of 260 $^\circ\text{C}$

[2] 4-Digit lot number XXXX

Information furnished by Analog Devices is believed to be accurate and reliable. However, no responsibility is assumed by Analog Devices for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of Analog Devices. Trademarks and registered trademarks are the property of their respective owners.



HMC724LC3

v03.0514

14 GBPS FAST RISE TIME 1:2 FANOUT BUFFER



Pin Descriptions [1]

Pin Number	Function	Description	Interface Schematic	
1, 4, 5, 8, 9, 12	GND	Signal Grounds		
2, 3 10, 11	D1P, D1N D2N, D2P	Differential Data Outputs, Current Mode Logic (CML) referenced to positive supply.	GND O GND DxP O DxN	
6, 7	DINP, DINN	Differential Data Inputs, Current Mode Logic (CML) referenced to positive supply.	GND O GND DINP O DINN	
13, 16	Vee	Negative Supply		
14, Package Base	GND	Supply Ground		
15	N/C	No Connection required. This pin may be connected to RF/DC ground without affecting performance.		

[1] Contact HMC for alternate pinouts

HIGH SPEED LOGIC - SMT

Information furnished by Analog Devices is believed to be accurate and reliable. However, no responsibility is assumed by Analog Devices for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of Analog Devices. Trademarks and registered trademarks are the property of their respective owners.



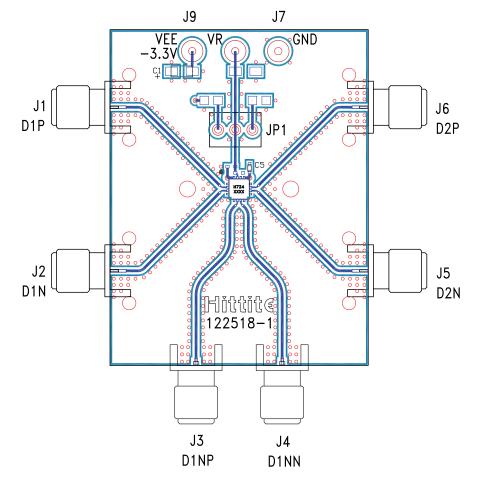
HMC724LC3

v03.0514



14 GBPS FAST RISE TIME 1:2 FANOUT BUFFER

Evaluation PCB



List of Materials for Evaluation PCB 122520 [1]

Item	Description
J1 - J6	PCB Mount SMA RF Connectors
J7, J9	DC Pin
C1	4.7 µF Capacitor, Tantalum
C5	100 pF, Capacitor 0402 Pkg.
U1	HMC724LC3 High Speed Logic, Fanout Buffer
PCB ^[2]	122518 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown. The exposed packaged base should be connected to GND. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

Information furnished by Analog Devices is believed to be accurate and reliable. However, no responsibility is assumed by Analog Devices for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of Analog Devices. Trademarks and registered trademarks are the property of their respective owners.

^[2] Circuit Board Material: Arlon 25FR or Rogers 4350

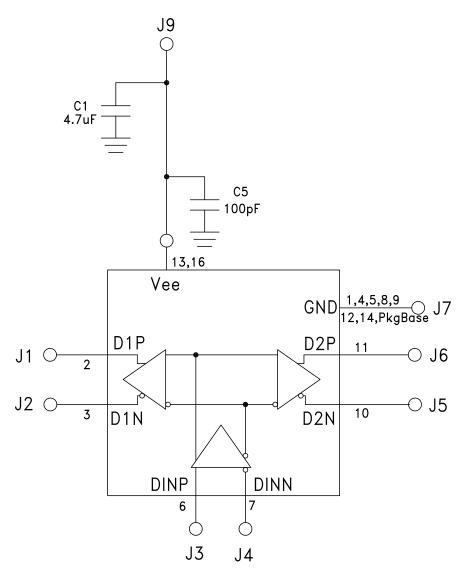


HMC724LC3

14 GBPS FAST RISE TIME 1:2 FANOUT BUFFER

ROHS

Application Circuit



Information furnished by Analog Devices is believed to be accurate and reliable. However, no responsibility is assumed by Analog Devices for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of Analog Devices. Trademarks and registered trademarks are the property of their respective owners.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Clock & Timer Development Tools category:

Click to view products by Analog Devices manufacturer:

Other Similar products are found below :

AD9517-0A/PCBZ AD9517-2A/PCBZ AD9522-4/PCBZ AD9520-5PCBZ AD9530/PCBZ AD9553/PCBZ ADCLK914PCBZ LMH2180SDEVAL DSC400-0333Q0032KE1-EVB TDGL013 MAX2750EVKIT ADCLK946PCBZ ADCLK946/PCBZ MAX2622EVKIT EKIT01-HMC1032LP6G Si5332-8IX-EVB Si5332-12IX-EVB RV-3029-C2-EVALUATION-BOARD-OPTION-B Si5332-6IX-EVB SKY72310-11-EVB EV1HMC8364LP6G RV-8263-C7-EVALUATION-BOARD EVK9FGV1002 EVK9FGV1008 EV1HMC6832ALP5L EVAL01-HMC830LP6GE EVAL01-HMC911LC4B EVAL01-HMC988LP3E TS3002DB 125605-HMC702LP6CE LMX2487E-EVM MIKROE-2481 2045 EKIT01-HMC835LP6G EKIT01-HMC834LP6GE TS3006DB DSC-TIMEFLASH2-KIT1 110227-HMC510LP5 110227-HMC513LP5 AD9515/PCBZ ADCLK948/PCBZ ADCLK954/PCBZ 112261-HMC739LP4 ADCLK925/PCBZ AD9522-0/PCBZ AD9520-4/PCBZ AC164147 DFR0469 LMK04133EVAL/NOPB LMH2191TMEVAL/NOPB